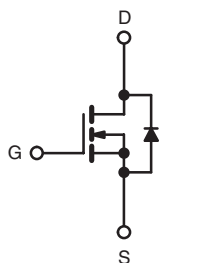


Power MOSFET

PRODUCT SUMMARY

V_{DS} (V)	500	
$R_{DS(on)}$ (Max.) (Ω)	$V_{GS} = 10\text{ V}$	0.13
Q_g (Max.) (nC)	180	
Q_{gs} (nC)	46	
Q_{gd} (nC)	71	
Configuration	Single	



N-Channel MOSFET

FEATURES

- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective C_{OSS} Specified
- Lead (Pb)-free Available



RoHS*
COMPLIANT

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGIES

- Full Bridge Converters
- Power Factor Correction Boost

ORDERING INFORMATION

Package	SUPER-247™
Lead (Pb)-free	IRFPS37N50APbF SiHFPS37N50A-E3
SnPb	IRFPS37N50A SiHFPS37N50A

ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	
Continuous Drain Current	$V_{GS} \text{ at } 10\text{ V}$	$T_C = 25\text{ }^\circ\text{C}$	A
		$T_C = 100\text{ }^\circ\text{C}$	
Pulsed Drain Current ^a	I_{DM}	144	
Linear Derating Factor		3.6	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy ^b	E_{AS}	1260	mJ
Repetitive Avalanche Current ^a	I_{AR}	36	A
Repetitive Avalanche Energy ^a	E_{AR}	44	mJ
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	446
Peak Diode Recovery dV/dt ^c	dV/dt	3.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25\text{ }^\circ\text{C}$, $L = 1.94\text{ mH}$, $R_G = 25\text{ }\Omega$, $I_{AS} = 36\text{ A}$ (see fig. 12).
- $I_{SD} \leq 36\text{ A}$, $dI/dt \leq 145\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.24	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.28	

SPECIFICATIONS $T_J = 25\text{ °C}$, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		500	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 30 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		-	-	25	μA
		V _{DS} = 400 V, V _{GS} = 0 V, T _J = 150 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 22 A ^b	-	-	0.13	Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 22 A ^b		20	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	5579	-	pF
Output Capacitance	C _{oss}			-	810	-	
Reverse Transfer Capacitance	C _{rss}			-	36	-	
Output Capacitance	C _{oss}	V _{GS} = 0 V	V _{DS} = 1.0 V , f = 1.0 MHz	-	7905	-	
Effective Output Capacitance	C _{oss eff.}		V _{DS} = 400 V , f = 1.0 MHz	-	221	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 36 A, V _{DS} = 400 V, see fig. 6 and 13 ^b	-	-	180	nC
Gate-Source Charge	Q _{gs}			-	-	46	
Gate-Drain Charge	Q _{gd}			-	-	71	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 250 V, I _D = 36 A, R _G = 2.15 Ω, R _D = 7.0 Ω, see fig. 10 ^b		-	23	-	ns
Rise Time	t _r			-	98	-	
Turn-Off Delay Time	t _{d(off)}			-	52	-	
Fall Time	t _f			-	80	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	36	A	
Pulsed Diode Forward Current ^a	I _{SM}		-	-	144		
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 36 A, V _{GS} = 0 V ^b		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 36 A, dI/dt = 100 A/μs ^b		-	570	860	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	8.6	13	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS} .